# Very Low Dropout/ Ultra Low Noise 5 Outputs Voltage Regulator

The MC33765 is an ultra low noise, very low dropout voltage regulator with five independent outputs which is available in TSSOP 16 surface mount package.

The MC33765 is available in 2.8 V. The output voltage is the same for all five outputs but each output is capable of supplying different currents up to 150 mA for output 4. The device features a very low dropout voltage (0.11 V typical for maximum output current), very low quiescent current (5.0  $\mu A$  maximum in OFF mode, 130  $\mu A$  typical in ON mode) and one of the output (output 3) exhibits a very low noise level which allows the driving of noise sensitive circuitry. Internal current and thermal limiting protections are provided.

Additionally, the MC33765 has an independent Enable input pin for each output. It includes also a common Enable pin to shutdown the complete circuit when not used. *The Common Enable pin has the highest priority over the five independent Enable input pins*.

The voltage regulators VR1, VR2 and VR3 have a common input voltage pin VCC1.

The other voltage regulators VR4 and VR5 have a common input voltage pin VCC2.

- Five Independent Outputs at 2.8V Typical, based upon voltage version
- Internal Trimmed Voltage Reference
- Vout Tolerance ±3.0% over the Temperature Range –40°C to +85°C
- Enable Input Pin (Logic–Controlled Shutdown) for Each of the Five Outputs
- Common Enable Pin to Shutdown the Whole Circuit
- Very Low Dropout Voltage (0.11 V Typical for Output 1, 2, 3 and 5;
   0.17 V Typical for Output 4 at Maximum Current)
- Very Low Quiescent Current (Maximum 5.0 μA in OFF Mode, 130 μA Typical in ON Mode)
- Ultra Low Noise for VR3 (30  $\mu$ V RMS Max, 100 Hz < f < 100 kHz)
- Internal Current and Thermal Limit
- 100 nF for VR1, VR2, VR4 and VR5 and 1.0 μF for VR3 for Stability
- Supply Voltage Rejection: 60 dB (Typical) @ f = 1.0 kHz



# ON Semiconductor

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### MARKING DIAGRAMS



TSSOP-16 DTB SUFFIX CASE 948F



= Assembly Location

NL, L = Wafer Lot

YY, Y = Year

WW, W = Work Week

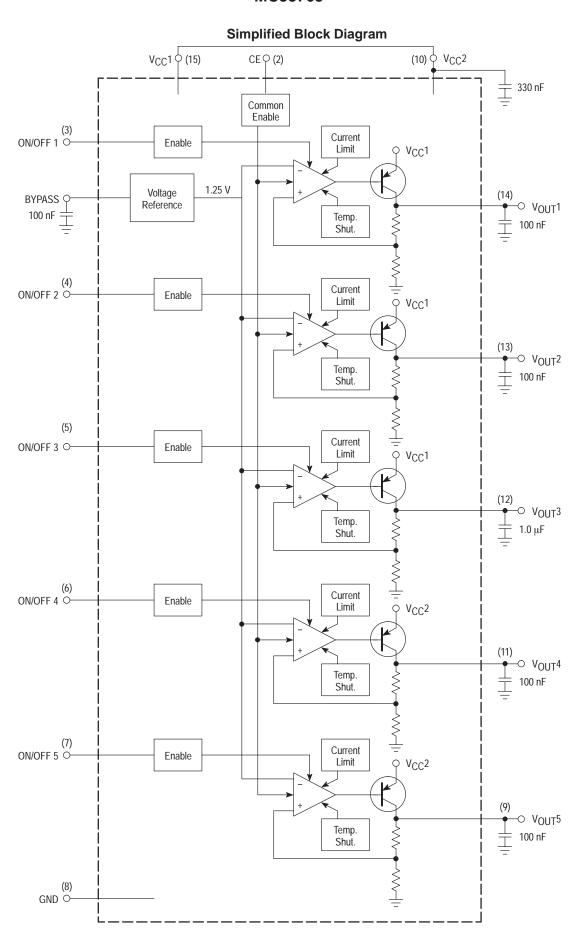
#### **PIN CONNECTIONS**

Bypass 1		16 Not Connected
Common Enable 2		15 V <sub>CC</sub> 1
On/Off V-Reg. 1 3	LC	14 Output V-Reg. 1
On/Off V-Reg. 2 4	929	13 Output V–Reg. 2
On/Off V-Reg. 3 5	MC337	12 Output V–Reg. 3
On/Off V-Reg. 4 6	Ĕ	11 Output V–Reg. 4
On/Off V-Reg. 5 7		10 V <sub>CC</sub> 2
GND 8		9 Output V–Reg. 5

(Top View)

#### ORDERING INFORMATION

Device	Package	Shipping
MC33765DTB	TSSOP16	96 Units/Rail
MC33765DTBR2	TSSOP16	2500 Units/Reel



#### **MAXIMUM RATINGS**

Rating	Symbol	Pin#	Value	Unit
Power Supply Voltage	Vcc		5.3	V
Thermal Resistance Junction-to-Air	$R_{\theta JA}$		140	°C/W
Operating Ambient Temperature	TA		-40 to +85	°C
Maximum Operating Junction Temperature	TJ		125	°C
Maximum Junction Temperature	T <sub>Jmax</sub>		150	°C
Storage Temperature Range	T <sub>stg</sub>		-60 to +150	°C

# **CONTROL ELECTRICAL CHARACTERISTICS**

**ELECTRICAL CHARACTERISTICS** (For typical values  $T_A = 25^{\circ}C$ , for min/max values  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ / Max  $T_J = 125^{\circ}C$ )

Characteristics	Symbol	Pin#	Min	Тур	Max	Unit
Independent Enable Pins	•			•		•
Input Voltage Range	VON/OFF(1-5)		0	_	Vcc	V
Control Input Impedance			100	_	-	kΩ
Logic "0", i.e. OFF State Logic "1", i.e. ON State	VON/OFF(1–5)		_ 2.0	- -	0.5 -	V
Common Enable Pin					•	
Input Voltage Range	VCE	2	0	_	Vcc	V
Control Input Impedance		2	100	_	-	kΩ
Logic "0", i.e. OFF State Logic "1", i.e. ON State	VCE	2	_ 2.0	_ _	0.3	V

**ELECTRICAL CHARACTERISTICS** (For typical values  $T_A = 25^{\circ}C$ , for min/max values  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ / Max  $T_J = 125^{\circ}C$ )

The state of the s							
Characteristics	Symbol	Min	Тур	Max	Unit		
CURRENT CONSUMPTION with NO LOAD							
Current Consumption at Logic "0" for the complete device, i.e. Common Enable and All Independent Enable pins at OFF State	IQ <sub>OFF</sub>	_	-	5.0	μΑ		
Current Consumption at Logic "1" for the complete device, i.e. Common Enable and All Independents Enable pins at ON State	IQ <sub>ON1</sub>	_	470	-	μΑ		
Current Consumption at Logic "1", Common Enable at ON State and All Independents Enable pins at OFF State	IQ <sub>ON2</sub>	-	130	-	μΑ		

# **REGULATOR ELECTRICAL CHARACTERISTICS**

**ELECTRICAL CHARACTERISTICS** (For typical values  $T_A = 25^{\circ}C$ , for min/max values  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ / Max  $T_J = 125^{\circ}C$ )

Characteristics	Symbol	Pin#	Min	Тур	Max	Unit
Supply and Output Voltages, Dropout and Load Regul	ation					
Supply Voltage V <sub>CC</sub> MC33765 (2.8V)	VCC1, VCC2	15, 10	3.0	3.6	5.3	V
Regulator Output Voltage for VR1, VR2, VR3, VR4 and VR5 MC33765 (2.8V)	VOUT(1-5)	14, 13, 12, 11, 9	2.7	2.8	2.85	V
Dropout Voltage for VR1, VR2, VR3, VR5 (Note 1.)	VCC-VOUT	14, 13, 12, 9	-	0.11	0.17	V
Dropout Voltage for VR4 (Note 1.)	VCC-VOUT4	11	-	0.17	0.30	V
Load Regulation (T <sub>A</sub> = 25°C)	Regload(1-5)	9, 11, 12, 13, 14	-	-	0.5	mV/ mA
Max Power Dissipation and Total DC Output Current (	∪ VR1 + VR2 + VR		R5) (Not	e 2.)		
Max Power Dissipation at $V_{CC} = 5.3 \text{ V } (T_A = 85^{\circ}\text{C})$ Max. Total RMS Output Current at $V_{CC} = 5.3 \text{ V } (T_A = 85^{\circ}\text{C})$	P <sub>dmax</sub> IRMS		- -		285 130	mW mA
Max Power Dissipation at $V_{CC}$ = 5.3 V ( $T_A$ = 25°C) Max. Total RMS Output Current at $V_{CC}$ = 5.3 V ( $T_A$ = 25°C)	P <sub>dmax</sub> IRMS		-		700 250	mW mA
Output Currents (Note 3.)						
Regulator VR1 Output Current	lOUT1	14	10	-	30	mA
Regulator VR2 Output Current	lOUT2	13	10	_	40	mA
Regulator VR3 Output Current	lOUT3	12	0	_	50	mA
Regulator VR4 Output Current	lOUT4	11	10	_	150	mA
Regulator VR5 Output Current	I <sub>OUT5</sub>	9	10	_	60	mA
Current Limit for VR1, VR2, VR3, VR4, VR5 [Twice the max Output Current for each output]	I <sub>MAX</sub>	14, 13, 12, 11, 9	-	2 X I <sub>OUT</sub> (1–5)	-	mA
External Capacitors						
External Compensation Capacitors for VR1, VR2, VR4, VR5	C <sub>(1-2, 4-5)</sub>	14, 13, 11, 9	0.10	_	1.0	μF
External Compensation Capacitors for VR3	C <sub>4</sub>	12	1.0	_	-	μF
External Compensation Capacitors ESR			0.05	1.0	3.0	Ω
Ripple Rejections						
Ripple Rejection VR1, VR2, VR4, VR5 (at Max. Current, 1.0 kHz, C = 100 nF)	$\frac{(\Delta V_{OUT})}{(\Delta V_{CC})}$	14, 13, 11, 9	50	60	-	dB
Ripple Rejection VR1, VR2, VR4, VR5 (at Max. Current, f = 10 kHz, C = 100 nF)	$\frac{{}^{(\Delta V}\!$	14, 13, 11, 9	40	45	_	dB
Ripple Rejection of VR3 $(\text{at Max. Current, f} = 1.0 \text{ kHz, C} = 1.0 \ \mu\text{F})$	$\frac{\frac{(\Delta V_{OUT})}{(\Delta V_{CC})}}$	12	50	60	-	dB
Ripple Rejection of VR3 $(\text{at Max. Current, f} = 10 \text{ kHz, C} = 1.0  \mu\text{F})$	$\frac{(\Delta V_{OUT})}{(\Delta V_{CC})}$	12	40	45	-	dB
Ripple Rejection of VR3 (at Max. Current, f = 100 kHz, C = 1.0 $\mu$ F)	$\frac{(\Delta^{V}OUT)}{(\Delta^{V}CC)}$	12	18	22	_	dB

<sup>1.</sup> Typical dropout voltages have been measured at currents: Output1: 25 mA, Output2: 35 mA, Output3: 40 mA, Output4: 140 mA, Output5: 40 mA Maximum value of dropout voltages are measured at maximum specified current.

<sup>2.</sup> See package power dissipation and thermal protection.

<sup>3.</sup> Maximum Output Currents are peak values. Total DC current have to be set upon maximum power dissipation specification. Only Output 3 has been designed to be stable at minimum current of 0 mA.

# **REGULATOR ELECTRICAL CHARACTERISTICS**

**ELECTRICAL CHARACTERISTICS** (For typical values  $T_A = 25^{\circ}C$ , for min/max values  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ /Max  $T_J = 125^{\circ}C$ )

Characteristics	Symbol	Min	Тур	Max	Unit
Dynamic Parameters					
Rise Time (1% 99%) Common Enable at ON state,					
C <sub>bypass</sub> = 10 nF, I <sub>out</sub> at max. current					
VR1, VR2, VR4, VR5 with $C_{OUT} = 100 \text{ nF}$ , $T_A = 25^{\circ}\text{C}$	ton	_	_	30	μs
VR3 with $C_{OUT}$ = 1.0 $\mu$ F, $T_A$ = 25°C		_	_	150	μS
Fall Time (99% 1%) [C <sub>OUT</sub> = 100 nF, I <sub>OUT</sub> = 30 mA] (Note 4.)	t <sub>off</sub>	_	100	_	μs
Overshoot (COUT = 100 nF for VR1, VR2, VR4, VR5					
and $C_{OUT}$ = 1.0 $\mu F$ for VR3) at $T_A$ = 25°C		_	5	8	%
Common Enable at ON state, independent enable from OFF to ON state					
Settling Time (to ±0.1% of nominal) at T <sub>A</sub> = 25°C					
Common Enable at ON state, independent enable from OFF to ON state		_	95	_	μs
Noise and Crosstalks					
Noise Voltage (100 Hz < f < 100 kHz) with C <sub>bypass</sub> = 100 nF					μV RMS
VR1, VR2, VR4, VR5 with C <sub>OUT</sub> = 100 nF		_	40	_	
VR3 with $C_{OUT} = 1.0 \mu F$		_	25	30	
Static crosstalk (DC shift) between the Regulator Output, T <sub>A</sub> = 25°C (Note 5.)		_	150	200	μV
Dynamic CrossTalk Attenuation between the Regulator Outputs		30	35	_	dB
(f = 10 kHz), T <sub>A</sub> = 25°C (Note 6.)					
Thermal Shutdown					
Thermal Shutdown		_	160	_	°C

<sup>4.</sup> The Fall time is highly dependent on the load conditions, i.e. load current for a specified value of C<sub>OUT</sub>.

<sup>5.</sup> Static Crosstalk is a DC shift caused by switching ON one of the outputs through independent enable to all other outputs. This parameter is highly dependent on overall PCB layout and requires the implementation of low–noise GROUND rules (e.g. Ground plane).

<sup>6.</sup> Dynamic crosstalk is the ratio between a forced output signal to signal transferred to other outputs. This requires special device configuration to be measured.

### MC33765 TYPICAL OSCILLOSCOPE SHOTS

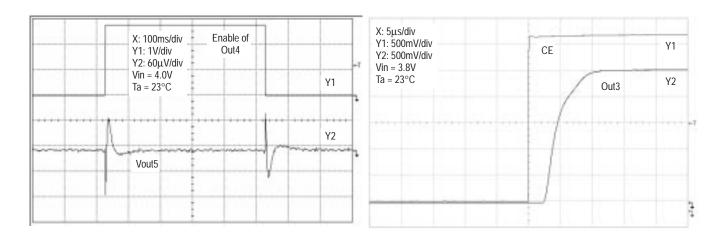


Figure 1. Crosstalk response of MC33765 showing extremely weak interaction between outputs
Output 4 is banged from 0 to 150mA

Figure 2. Repetitive Common Enable response time

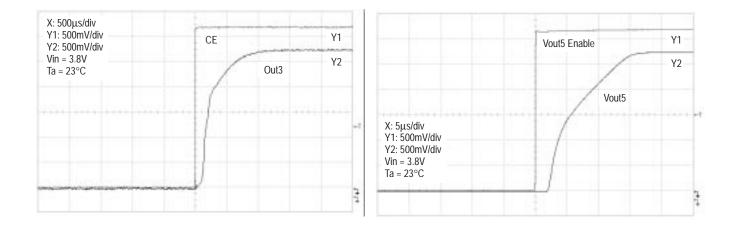


Figure 3. Single Common Enable response time (Cbypass discharged)

Figure 4. Output response from seperate Enable

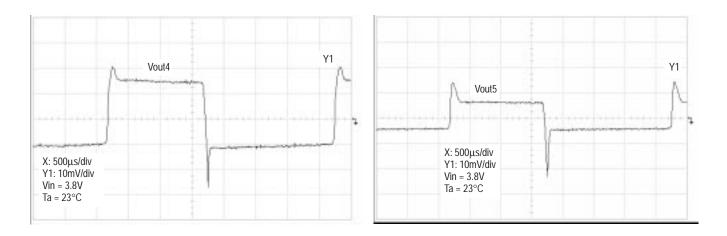


Figure 5. Output 4 is banged from 3mA to 150mA

Figure 6. Output 5 is banged from 3mA to 50mA

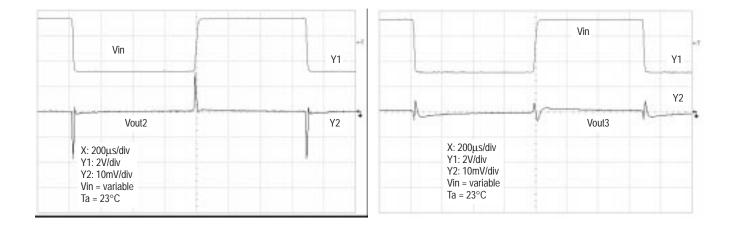
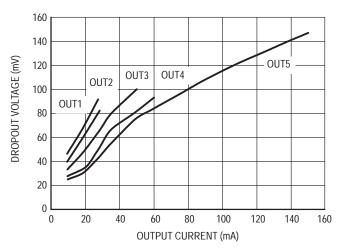


Figure 7. Typical input voltage rejection (Cout = 100nF)

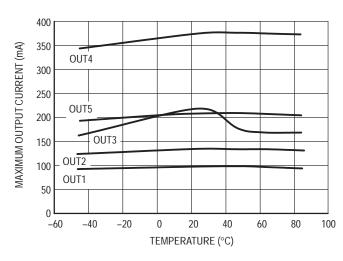
Figure 8. Typical input voltage rejection (Cout =  $1\mu$ F)



8.0 OUT4 7.0 GROUND CURRENT (mA) 6.0 OUT2 5.0 4.0 OUT3 3.0 2.0 OUT1 1.0 0 40 100 -60 -40 -20 0 20 60 80 TEMPERATURE (°C)

Figure 9. Dropout Voltage versus Output Current

Figure 10. Ground Current versus Individual Output



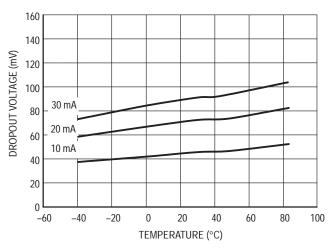
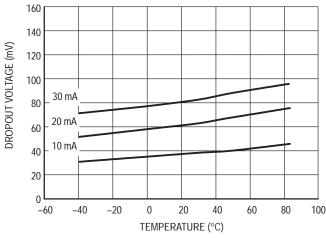
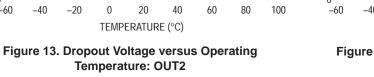


Figure 11. Maximum Output Current versus Temperature

Figure 12. Dropout Voltage versus Operating Temperature: OUT1





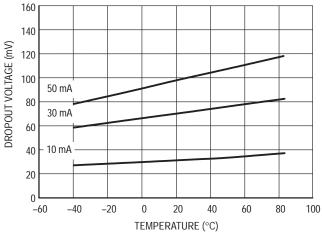
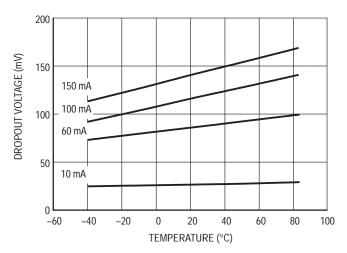


Figure 14. Dropout Voltage versus Operating Temperature: OUT3



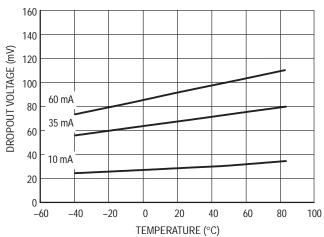


Figure 15. Dropout Voltage versus Operating Temperature: OUT4

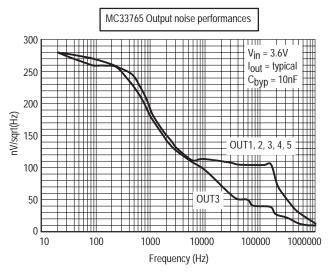
Figure 16. Dropout Voltage versus Operating Temperature: OUT5

#### **DEFINITIONS**

**Load Regulation** – The change in output voltage for a change in load current at constant chip temperature.

**Dropout Voltage** – The input/output differential at which the regulator output no longer maintains regulation against further reductions in input voltage. Measured when the output drops 100 mV below its nominal value (which is measured at 1.0 V differential input/output), dropout voltage is affected by junction temperature, load current and minimum input supply requirements.

**Output Noise Voltage** – The RMS AC voltage at the output with a constant load and no input ripple, measured over a specified frequency range.



**Maximum Power Dissipation** – The maximum total dissipation for which the regulator will operate within specifications.

**Quiescent Current** – Current which is used to operate the regulator chip with no load current.

**Line Regulation** – The change in input voltage for a change in the input voltage. The measurement is made under conditions of low dissipation or by using pulse techniques such that the average chip temperature is not significantly affected.

**Thermal Protection** – Internal thermal shutdown circuitry is provided to protect the integrated circuit in the event that the maximum junction temperature is exceeded. When activated, typically 160°C, the regulator turns off. This feature is provided to prevent catastrophic failures from accidental overheating.

Maximum Package Power Dissipation and RMS Current – The maximum package power dissipation is the power dissipation level at which the junction temperature reaches its maximum value i.e. 125°C. The junction temperature is rising while the difference between the input power (V<sub>CC</sub> X I<sub>CC</sub>) and the output power (V<sub>out</sub> X I<sub>out</sub>) is increasing.

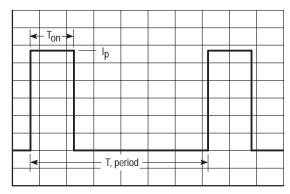
As MC33765 device exhibits five independent outputs  $I_{\text{out}}$  is specified as the maximum RMS current combination of the five output currents.

As the device can be switched ON/OFF through independent Enable (ON/OFF pin) or Common Enable, the output signal could be, for example, a square wave. Let's assume that the device is ON during ToN on a signal period T. The RMS current will be given by:

$$I_{out_{RMS}} = I_{P} \times \sqrt{D}$$

where

$$D = \frac{T_{ON}}{T}$$



Depending on ambient temperature, it is possible to calculate the maximum power dissipation and so the maximum RMS current as following:

$$Pd = \frac{T_J - T_A}{R_{\Theta I \Delta}}$$

The maximum operating junction temperature  $T_J$  is specified at 125°C, if  $T_A = 25$ °C, then  $P_D = 700$  mW. By neglecting the quiescent current, the maximum power dissipation can be expressed as:

$$I_{out} = \frac{P_D}{V_{CC} - V_{out}}$$

So that in the more drastic conditions:

 $V_{CC} = 5.3 \text{ V}$ ,  $V_{out} = 2.7 \text{ V}$  then the maximum RMS value of  $I_{out}$  is 269 mA.

The maximum power dissipation supported by the device is a lot increased when using appropriate application design. Mounting pad configuration on the PCB, the board material and also the ambient temperature are affected the rate of temperature rise. It means that when the I<sub>C</sub> has good thermal conductivity through PCB, the junction temperature will be "low" even if the power dissipation is great.

The thermal resistance of the whole circuit can be evaluated by deliberately activating the thermal shutdown of the circuit (by increasing the output current or raising the input voltage for example).

Then you can calculate the power dissipation by subtracting the output power from the input power. All variables are then well known: power dissipation, thermal shutdown temperature (160°C for MC33765) and ambient temperature.

$$R_{\theta JA} = \frac{T_J - T_A}{P_D}$$

# DESIGN HINTS Reducing the cross-talk between the MC33765 outputs

One of the origin of the DC shift finds its seat in the layout surrounding the integrated circuit. Particular care has to be taken when routing the output ground paths. Star grounding or a ground plane are the absolute conditions to reduce the noise or shift associated to common impedance situations, as depicted by Figure 17.

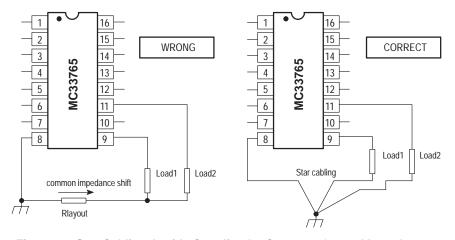


Figure 17. Star Cabling Avoids Coupling by Common Ground Impedance

The first left cabling will generate a voltage shift which will superimpose on the output voltages, thus creating an undesirable offset. By routing the return grounds to a single low impedance point, you naturally shield the circuit against common impedance disturbances. Figure 18 portraits the text fixture implemented to test the response of the MC33765.

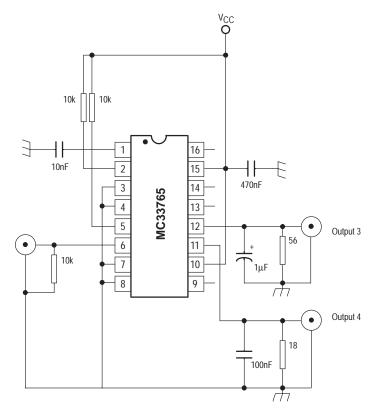


Figure 18. DC Shift Text Fixture

# **DESIGN HINTS (cont.)**

Output 4 was banged from 0 to 150mA via its dedicated control pin, while output 3 fixed at 50mA was monitored. The circuit has been implemented on a PCB equipped with a

ground plane and routed with short copper traces. The results are shown hereafter, revealing the excellent behavior of the MC33765 when crosstalks outputs is at utmost importance.

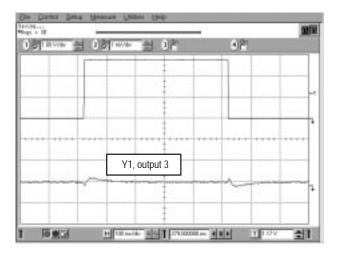


Figure 19. Vin = 4V, Y1 =  $62.5\mu V/div$ , F = 200Hz

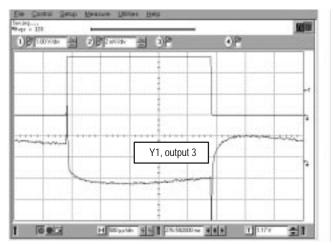


Figure 20. Vin = 5V, Y1 = 1mV/div

#### **TECHNICAL TERMS**

**Rise Time** – Common Enable being in ON state, the device is switched on by ON/OFF pin control.

Let's call t<sub>1</sub> the time when ON/OFF signal reaches 1% of its nominal value.

Let's call t2 the time when output signal reaches 99% of its nominal value.

The rise time for this device is specified as:

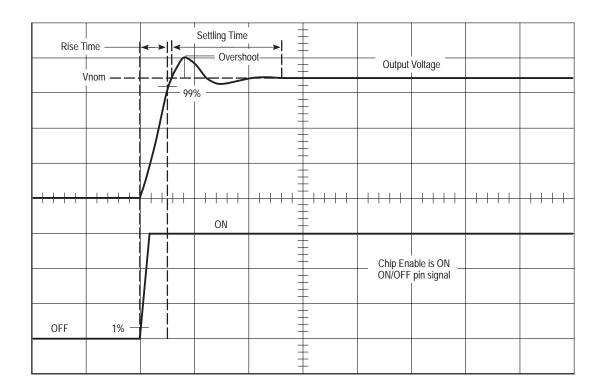
$$t_{ON} = t_1 - t_2$$

**Fall Time** – The fall time is highly dependent on the output capacitor and so device design is not impacting at all this parameter.

**Overshoot, Settling Time** – As regulators are based on regulation loop through an error amplifier, this type of device requires a certain time to stabilize and reach its nominal value.

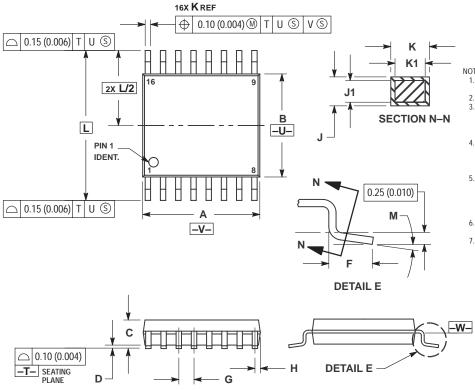
The overshoot is defined as the voltage difference between the peak voltage and steady state when switching ON the regulator.

The settling time is equal to the time required by the regulator to stabilize to its nominal value ( $\pm 0.5\%$ ) after peak value when switching ON the regulator.



#### **PACKAGE DIMENSIONS**

TSSOP-16 **DTB SUFFIX** CASE 948F-01 **ISSUE O** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- OR GATE BURRS SHALL NOT EXCEED 0.15
  (0.006) PER SIDE.

  4. DIMENSION B DOES NOT INCLUDE INTERLEAD
  FLASH OR PROTRUSION. INTERLEAD FLASH OR
  PROTRUSION SHALL NOT EXCEED
  0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR
  PROTRUSION ALL OWABLE DAMBAR
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  TERMINAL NUMBERS ARE SHOWN FOR DETERMINE ONLY.
- REFERENCE ONLY.

  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INC	HES					
DIM	MIN	MAX	MIN	MAX					
Α	4.90	5.10	0.193	0.200					
В	4.30	4.50	0.169	0.177					
С	1.20 0.05 0.15			0.047					
D			0.002	0.006					
F	0.50	0.75	0.020	0.030					
G	0.65	BSC	0.026	BSC					
Н	0.18	0.28	0.007	0.011					
J	0.09	0.20	0.004	0.008					
J1	0.09	0.16	0.004	0.006					
K	0.19	0.30	0.007	0.012					
K1	0.19	0.25	0.007	0.010					
L	6.40		0.252						
M	0°	8°	0°	8 °					

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